



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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2SC4626J

Silicon NPN epitaxial planar type

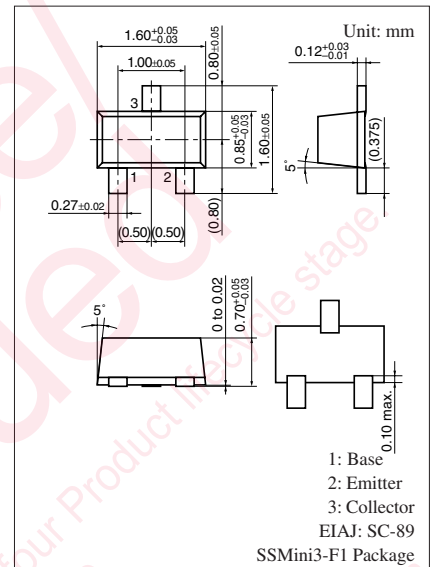
For high-frequency amplification

■ Features

- Optimum for RF amplification of FM/AM radios
- High transition frequency f_T
- SS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|---------------------------------------|-----------|-------------|------------------|
| Collector-base voltage (Emitter open) | V_{CBO} | 30 | V |
| Collector-emitter voltage (Base open) | V_{CEO} | 20 | V |
| Emitter-base voltage (Collector open) | V_{EBO} | 5 | V |
| Collector current | I_C | 30 | mA |
| Collector power dissipation | P_C | 125 | mW |
| Junction temperature | T_j | 125 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -55 to +125 | $^\circ\text{C}$ |



Marking Symbol: V

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

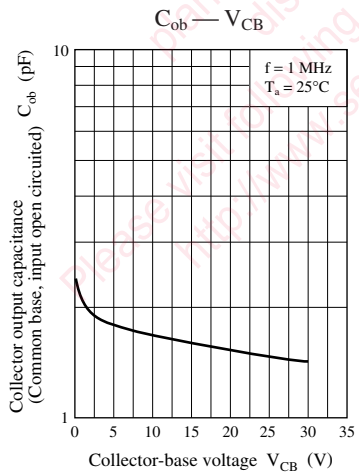
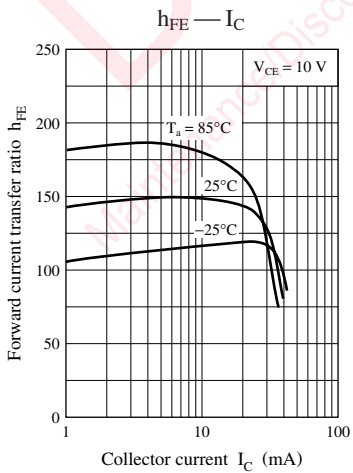
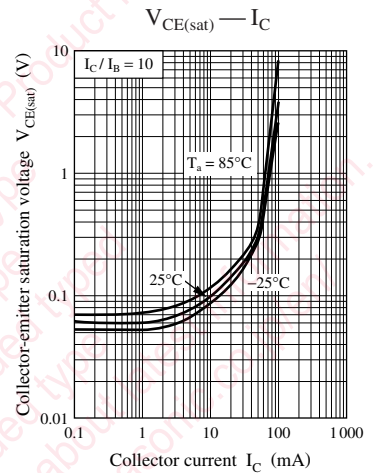
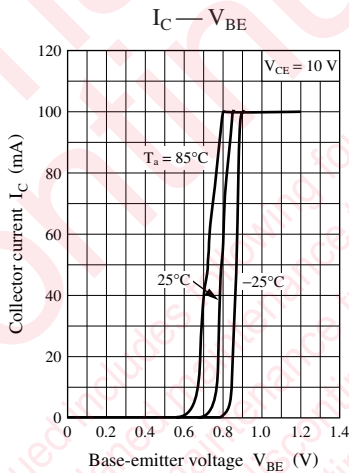
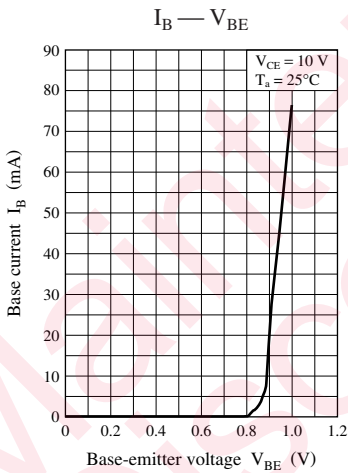
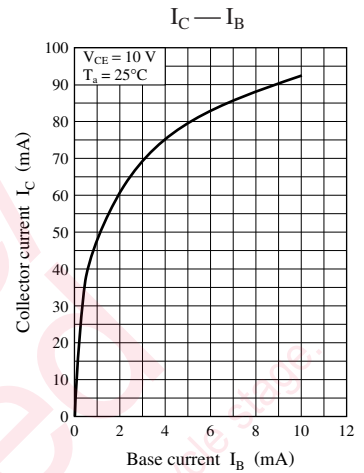
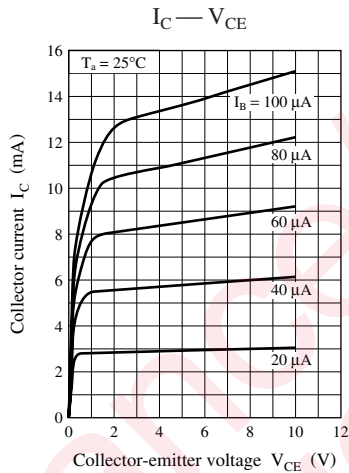
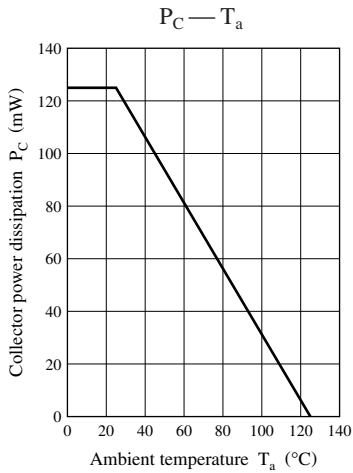
| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|--|-----------|---|-----|-----|-----|---------------|
| Collector-base cutoff current (Emitter open) | I_{CBO} | $V_{CB} = 10\text{ V}, I_E = 0$ | | | 0.1 | μA |
| Forward current transfer ratio * | h_{FE} | $V_{CB} = 10\text{ V}, I_E = -1\text{ mA}$ | 70 | | 220 | — |
| Transition frequency | f_T | $V_{CB} = 10\text{ V}, I_E = -1\text{ mA}, f = 200\text{ MHz}$ | 150 | 250 | | MHz |
| Noise figure | NF | $V_{CB} = 10\text{ V}, I_E = -1\text{ mA}, f = 5\text{ MHz}$ | | 2.8 | 4.0 | dB |
| Reverse transfer impedance | Z_{rb} | $V_{CB} = 10\text{ V}, I_E = -1\text{ mA}, f = 2\text{ MHz}$ | | 22 | 50 | Ω |
| Common-emitter reverse transfer capacitance | C_{re} | $V_{CB} = 10\text{ V}, I_E = -1\text{ mA}, f = 10.7\text{ MHz}$ | | 0.9 | 1.5 | pF |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

| Rank | B | C | No-rank |
|----------|-----------|------------|-----------|
| h_{FE} | 70 to 140 | 110 to 220 | 70 to 220 |

Product of no-rank is not classified and have no indication for rank.



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